



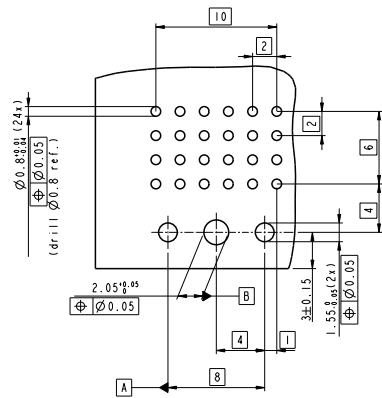


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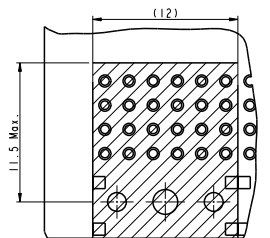
All items mentioned on this sheet are recommendations of FCI and should be seen as indication. The final responsibility for the application process is at the customer.

**PCB LAYOUT: HOLE PATTERN**

PCB thickness 1.4 - 2.6 mm.

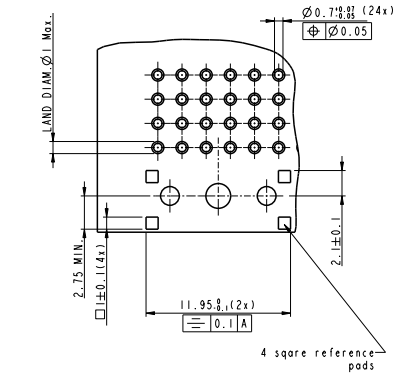


**PCB LAYOUT: BOARD AREA**



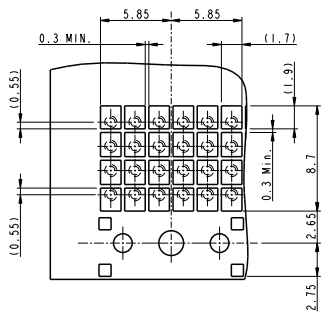
**PCB LAYOUT: PLATING**

Plating thickness must be constant over the connector area. Copper layer 50 µm max. Solder mask should cover all surfaces under the paste that are not plated. There is no solder mask allowed on the reference pads.



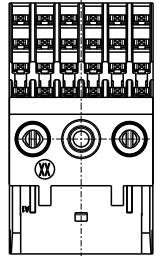
**PCB LAYOUT : SOLDER PASTE**

Recommended stencil thickness 0.15 mm. The solder content in the paste should be sufficient, typically 50% volume percentage. The solder tail, PCB, stencil and application process determine the solder result. The squeegee process (angle, speed, pressure, material and number of cycles) must be optimized, so that sufficient solder is available.



**CONNECTOR MOUNTING**

The connector can be picked up with a mechanical gripper or a vacuum nozzle. Nozzle diameter 6 - 10 mm. Both metal nozzles or nozzles with seal or rubber can be used. Vacuum pressure 0.6 bar under local ambient pressure. Position of the nozzle on the connector as mentioned on sheet 1. The reference for placing the connector can be determined by video inspection of the connector bottomside. The recesses of the retention pegs are designed for video recognition (shown bold, see sketch below). The line through the center of the recesses is the reference for Y-direction and rotation; datum B. The line through the middle between the center of the recesses perpendicular to the first line is reference for X-direction; datum A.



The acceleration and the deceleration of the mounting head of the pick and place equipment should be restricted in such a way that the connector doesn't fall or slides on the nozzle. An inferior accuracy of the placing equipment can reduce the success rate of mounting. The fast movement of the connector must be purely vertical and downwards. The board must be horizontal. The final mounting force must be controlled in such a way that the connector is seated flush to the board and remains there after releasing from the placing device. (Extra) PCB support can be required to meet this. The movement of the PCB-assembly before reflowing must be smooth so that all components remain seated flush on the board.

Material	-	Spec. ref.	-
Mat. code	-	surface	✓ tolerance
Heat treat	-	ISO 406	ISO 1101
Plating/Finish	-	ISO 1302	ISO 1101
Dr. IP Partner	2002/07/15	Product family	METRAL (TW)
Eng. P. Potlert	020117	Model Name	52048 ECN
Chr. P. Potlert	2002/02/14	Model Revision	E REL Level
App. P. Potlert	2002/04/19	Scale	A1 S:1
Proj. file	catalog no	customer copy	sheet 2 of 2